

CHIP QUIK®

TC1-10G

**Heat Sink Compound, Thermally conductive, High Density,
Syringe, 10 g**



- High density thermal paste
- White, non-curing and non-flowing thermally conductive heat sink compound
- Heavily filled with heat-conductive metal oxide
- Provides high thermal conductivity, low bleed and high temperature stability
- Electrically insulating (2x 10¹⁵ ohm-cm)